



Nidec Advance Technology Corporation

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Nidec Advance Technology to Exhibit Products at SEMICON SEA 2026

Nidec Advance Technology Corporation (“Nidec Advance Technology” or the “Company”) today announced its participation in SEMICON Southeast Asia 2026, to be held from May 5 to May 7, 2026, at the Malaysia International Trade & Exhibition Centre (MITEC) in Kuala Lumpur.



At SEMICON SEA 2026, Nidec Advance Technology will present its latest portfolio of advanced inspection and testing solutions for the semiconductor industry. The highlights technologies that support advanced semiconductor manufacturing, advanced packaging, and power devices.

On display will be optical 2D/3D and AI-based wafer inspection systems (RWi-300MK3 & AURCA-S series), large tray-ready 3D and AFVI + AI inspection systems for large substrates (RSH & AURCA series), as well as IGBT/SiC power module inspection equipment (NATS series) and conduction and short-circuit inspection systems for packages (GATS series).

In addition to its core lineup, Nidec SV Probe will be exhibiting a variety of its testing solutions including MEMS-based probe cards, fine pitch probes and our newest probe card technologies, Chamber Head, Thermo-coupling and Glass Micro-hole processing.

Nidec SV Probe’s MEMS-based and fine pitch probing solutions are ideal for complex logic ICs for next-generation AI, automotive and applications. This emergence of AI and the rise of EV vehicles have also expedited the need for more reliable and efficient testing product capabilities. Nidec SV Probe’s latest technological developments on display will be the

Chamber Head probe card for power devices, the Thermo-coupling Probe for temperature measurement, and the Glass Micro-hole Processing for better manufacturing capability and boosted productivity.

About SEMICON SEA 2025:

- Period: Tuesday, May 5 – Thursday, May 7, 2026
- Venue: Malaysia International Trade & Exhibition Centre (MITEC) in Kuala Lumpur.
- Booth: Level 2, Booth#2396
- Official website: <https://expo.semi.org/southeastasia2026/public/enter.aspx>

Nidec Advance Technology's exhibits will include:

- Optical 2D/3D inspection equipment for semiconductor wafers (RWi-300MK3 series)
- Optical 2D + AI inspection equipment for semiconductor wafers (AURCA-S series)
- Large Tray-Ready 3D Inspection System for Large Substrates (RSH Series)
- Large Tray-Ready AFVI + AI Inspection System for Large Substrates (AURCA Series)
- IGBT/SiC power module inspection equipment (NATS series)
- Conduction/short-circuit inspection equipment for semiconductor packages (GATS series)
- Pin probe for ultra-high-precision inspections
- Semiconductor wafer inspection probe card